

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of :

Choung Hyep Lee et al. :

Serial No. [NEW] :

Filed: April 13, 2004 :

APPARATUS FOR AND METHOD OF HEAT-TREATING A WAFER

PRELIMINARY AMENDMENT

U.S. Patent and Trademark Office
2011 South Clark Place
Customer Window, **Mail Stop Patent Application**
Crystal Plaza Two, Lobby, Room 1B03
Arlington, VA 22202

Sir:

Preliminary to the examination of the above-identified application, please
amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins
of page 3 of this paper.

Remarks begin on page 5 of this paper.